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FAIRCHILD SEMICONDUCTOR®

November 2013

# FDB14N30

## N-Channel UniFET™ MOSFET

### 300 V, 14 A, 290 mΩ

## Features

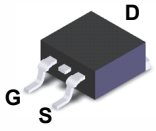
- $R_{DS(on)}$ = 290 mΩ (Max.) @ $V_{GS}$ = 10 V, $I_D$ = 7 A
- Low Gate Charge (Typ. 18 nC)
- Low $C_{rss}$ (Typ.17 pF)
- 100% Avalanche Tested
- Improved dv/dt Capability

## Applications

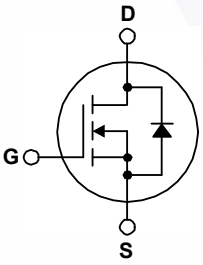
- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply

## Description

UniFET™ MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.




$D^2$-PAK




## Absolute Maximum Ratings $T_C$ = 25°C unless otherwise noted.

| Symbol | Parameter | | FDB14N30TM | Unit |
|---|---|---|---|---|
| $V_{DSS}$ | Drain-Source Voltage | | 300 | V |
| $I_D$ | Drain Current | - Continuous ($T_C$ = 25°C)<br>- Continuous ($T_C$ = 100°C) | 14<br>8.4 | A<br>A |
| $I_{DM}$ | Drain Current | - Pulsed (Note 1) | 56 | A |
| $V_{GSS}$ | Gate-Source voltage | | ±30 | V |
| $E_{AS}$ | Single Pulsed Avalanche Energy | (Note 2) | 330 | mJ |
| $I_{AR}$ | Avalanche Current | (Note 1) | 14 | A |
| $E_{AR}$ | Repetitive Avalanche Energy | (Note 1) | 14 | mJ |
| dv/dt | Peak Diode Recovery dv/dt | (Note 3) | 4.5 | V/ns |
| $P_D$ | Power Dissipation | ($T_C$ = 25°C)<br>- Derate above 25°C | 140<br>1.12 | W<br>W/°C |
| $T_J$, $T_{STG}$ | Operating and Storage Temperature Range | | -55 to +150 | °C |
| $T_L$ | Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds | | 300 | °C |

## Thermal Characteristics

| Symbol | Parameter | FDB14N30TM | Unit |
|---|---|---|---|
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case, Max | 0.87 | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient (minimum pad of 2 oz copper), Max. | 62.5 | |
| | Thermal Resistance, Junction to Ambient (1 $in^2$ pad of 2 oz copper), Max. | 40 | |

## Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|---|---|---|---|---|---|
| FDB14N30 | FDB14N30TM | D2-PAK | 330mm | 24mm | 800 units |

## Electrical Characteristics $T_C$ = 25°C unless otherwise noted.

| Symbol | Parameter | Conditions | Min. | Typ. | Max | Unit |
|---|---|---|---|---|---|---|
| **Off Characteristics** | | | | | | |
| $BV_{DSS}$ | Drain-Source Breakdown Voltage | $V_{GS}$ = 0V, $I_D$ = 250μA | 300 | -- | -- | V |
| $\Delta BV_{DSS}$ / $\Delta T_J$ | Breakdown Voltage Temperature Coefficient | $I_D$ = 250μA, Referenced to 25°C | -- | 0.3 | -- | V/°C |
| $I_{DSS}$ | Zero Gate Voltage Drain Current | $V_{DS}$ = 300V, $V_{GS}$ = 0V<br>$V_{DS}$ = 240V, $T_C$ = 125°C | --<br>-- | --<br>-- | 1<br>10 | μA<br>μA |
| $I_{GSSF}$ | Gate-Body Leakage Current, Forward | $V_{GS}$ = 30V, $V_{DS}$ = 0V | -- | -- | 100 | nA |
| $I_{GSSR}$ | Gate-Body Leakage Current, Reverse | $V_{GS}$ = -30V, $V_{DS}$ = 0V | -- | -- | -100 | nA |
| **On Characteristics** | | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}$ = $V_{GS}$, $I_D$ = 250μA | 3.0 | -- | 5.0 | V |
| $R_{DS(on)}$ | Static Drain-Source On-Resistance | $V_{GS}$ = 10V, $I_D$ = 7A | -- | 0.24 | 0.29 | Ω |
| $g_{FS}$ | Forward Transconductance | $V_{DS}$ = 40V, $I_D$ = 7A | -- | 10.5 | -- | S |
| **Dynamic Characteristics** | | | | | | |
| $C_{iss}$ | Input Capacitance | $V_{DS}$ = 25V, $V_{GS}$ = 0V, f = 1.0MHz | -- | 815 | 1060 | pF |
| $C_{oss}$ | Output Capacitance | | -- | 150 | 195 | pF |
| $C_{rss}$ | Reverse Transfer Capacitance | | -- | 17 | 25 | pF |
| **Switching Characteristics** | | | | | | |
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD}$ = 150V, $I_D$ = 14A<br>$R_G$ = 25Ω | -- | 20 | 50 | ns |
| $t_r$ | Turn-On Rise Time | | -- | 105 | 120 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | -- | 30 | 70 | ns |
| $t_f$ | Turn-Off Fall Time | (Note 4) | -- | 75 | 160 | ns |
| $Q_g$ | Total Gate Charge | $V_{DS}$ = 240V, $I_D$ = 14A<br>$V_{GS}$ = 10V | -- | 18 | 25 | nC |
| $Q_{gs}$ | Gate-Source Charge | | -- | 4.5 | -- | nC |
| $Q_{gd}$ | Gate-Drain Charge | (Note 4) | -- | 8 | -- | nC |
| **Drain-Source Diode Characteristics and Maximum Ratings** | | | | | | |
| $I_S$ | Maximum Continuous Drain-Source Diode Forward Current | | -- | -- | 14 | A |
| $I_{SM}$ | Maximum Pulsed Drain-Source Diode Forward Current | | -- | -- | 56 | A |
| $V_{SD}$ | Drain-Source Diode Forward Voltage | $V_{GS}$ = 0V, $I_S$ = 14A | -- | -- | 1.4 | V |
| $t_{rr}$ | Reverse Recovery Time | $V_{GS}$ = 0V, $I_S$ = 14A<br>$dI_F/dt$ =100A/μs | -- | 235 | -- | ns |
| $Q_{rr}$ | Reverse Recovery Charge | | -- | 1.6 | -- | μC |

**NOTES:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L = 2.8mH, $I_{AS}$ = 14A, $V_{DD}$ = 50V, $R_G$ = 25Ω, Starting $T_J$ = 25°C
3. $I_{SD}$ ≤ 14A, di/dt ≤ 200A/μs, $V_{DD}$ ≤ $BV_{DSS}$, Starting $T_J$ = 25°C
4. Essentially Independent of Operating Temperature Typical Characteristics

## Typical Characteristics

**Figure 1. On-Region Characteristics**

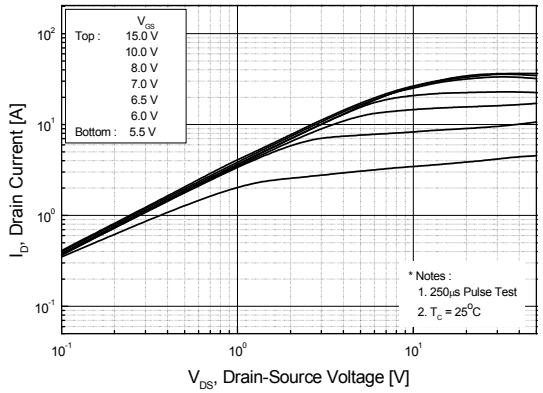



**Figure 2. Transfer Characteristics**

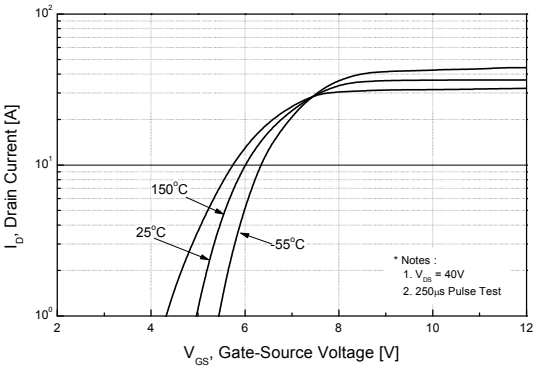



**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**

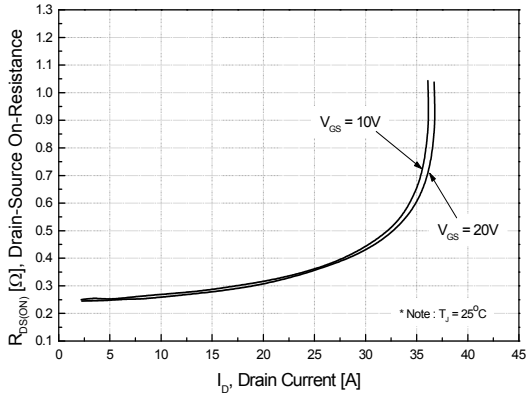



**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue**

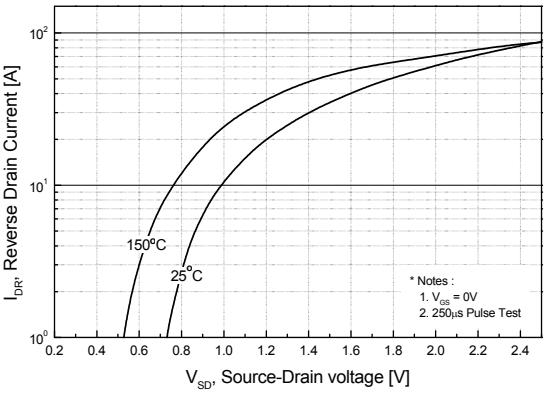



**Figure 5. Capacitance Characteristics**

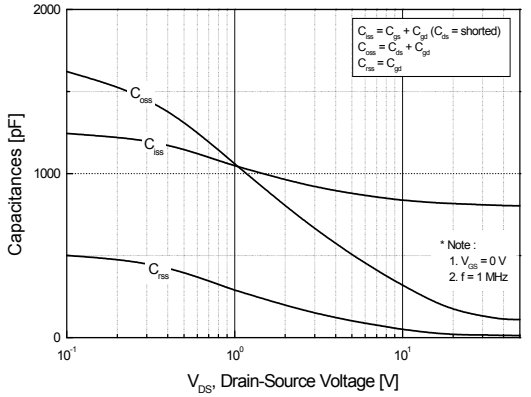
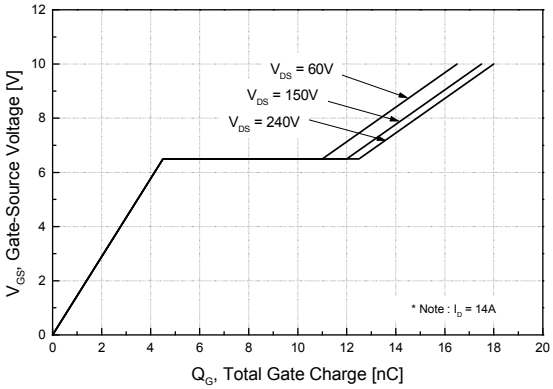



**Figure 6. Gate Charge Characteristics**



## Typical Characteristics (Continued)

**Figure 7. Breakdown Voltage Variation vs. Temperature**

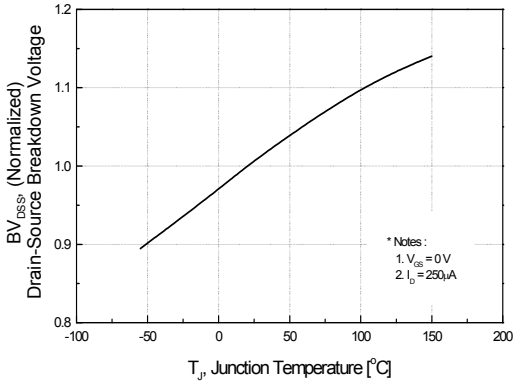



**Figure 8. On-Resistance Variation vs. Temperature**

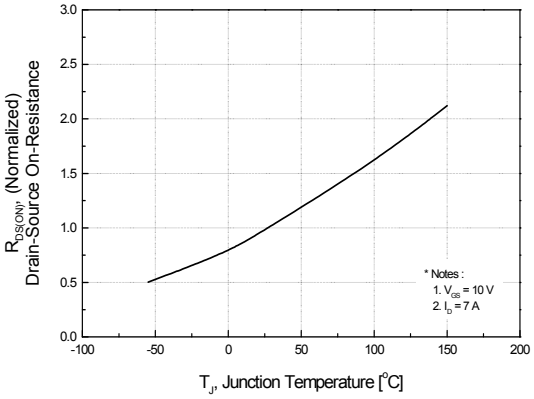



**Figure 9. Maximum Safe Operating Area**

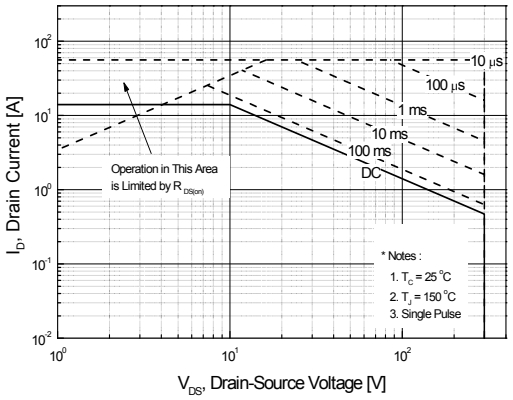



**Figure 10. Maximum Drain Current vs. Case Temperature**

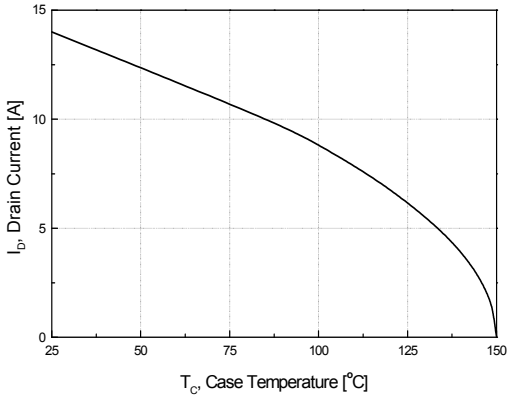



**Figure 11. Transient Thermal Response Curve**

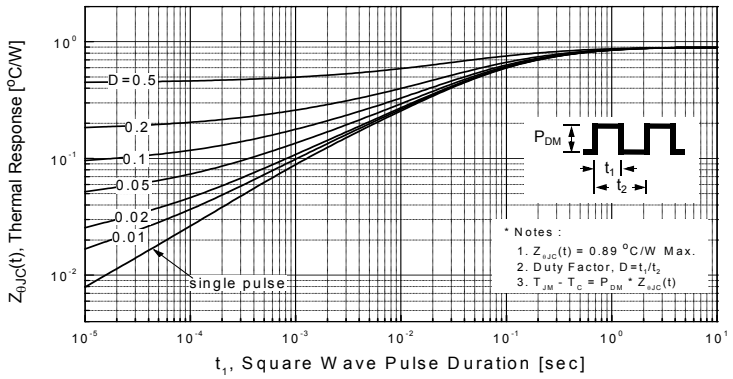


**Figure 12. Gate Charge Test Circuit & Waveform**

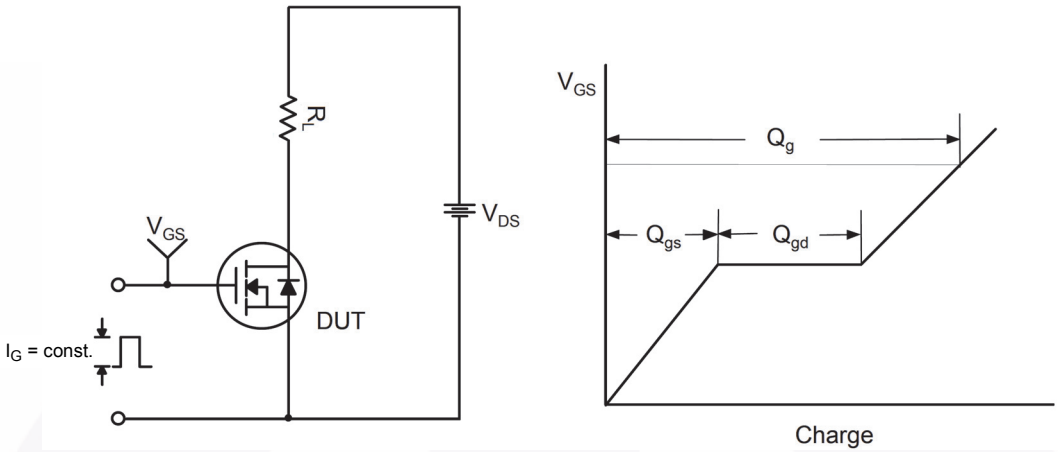



**Figure 13. Resistive Switching Test Circuit & Waveforms**

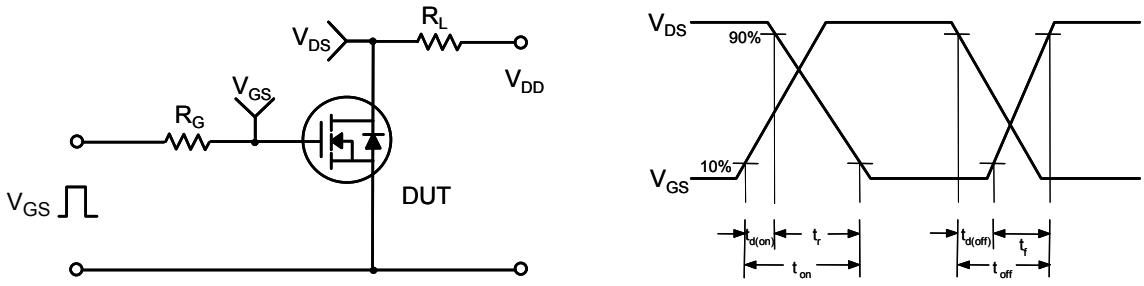



**Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms**

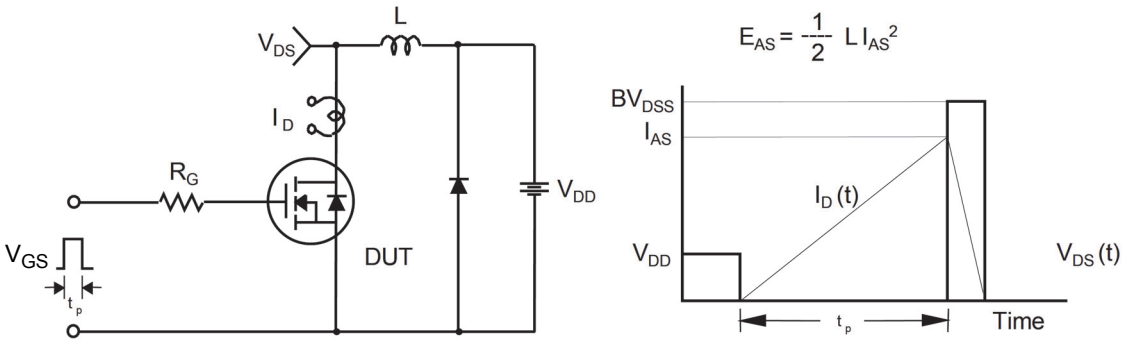
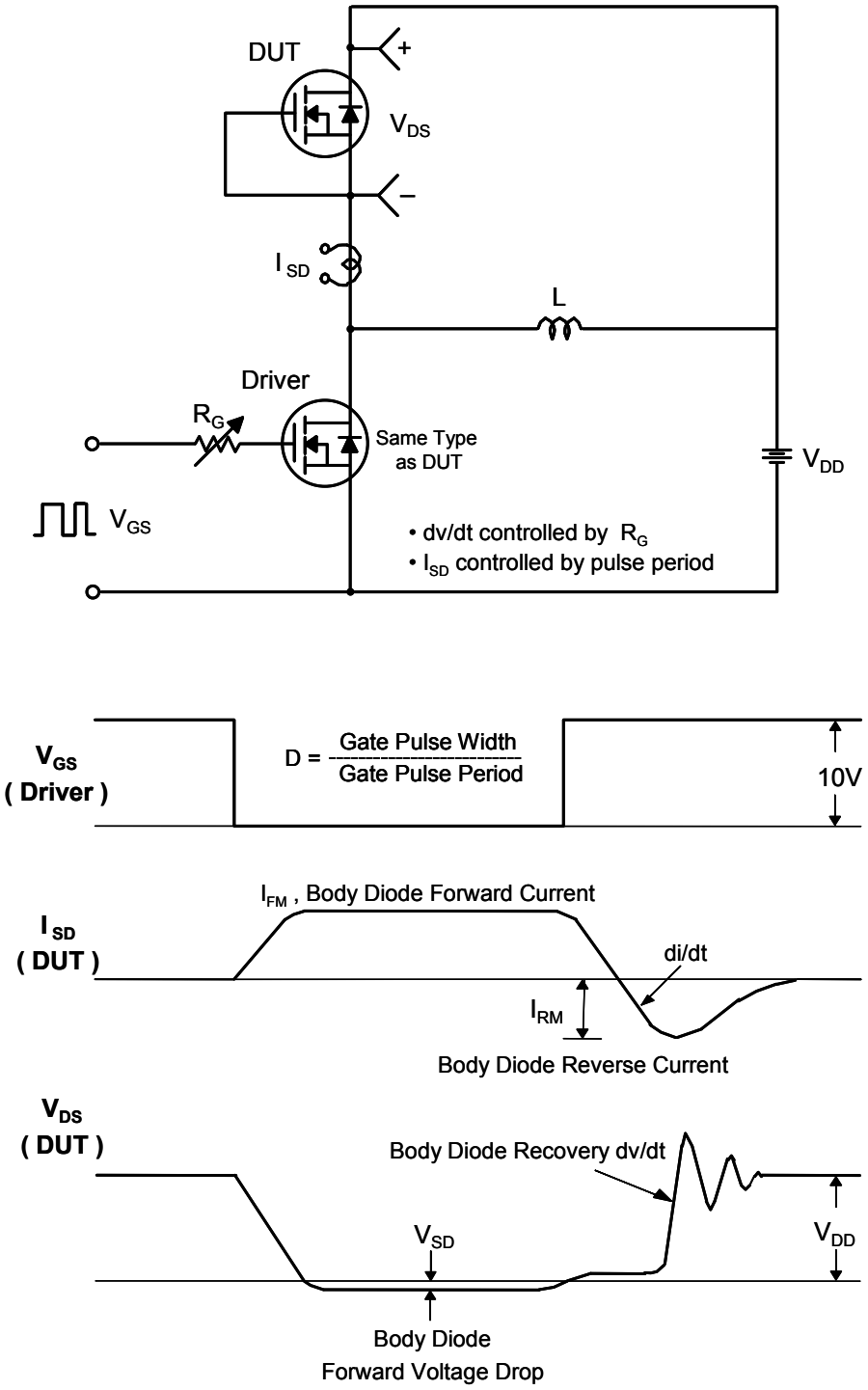


**Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms**



## Mechanical Dimensions

# TO-263 2L (D²PAK)

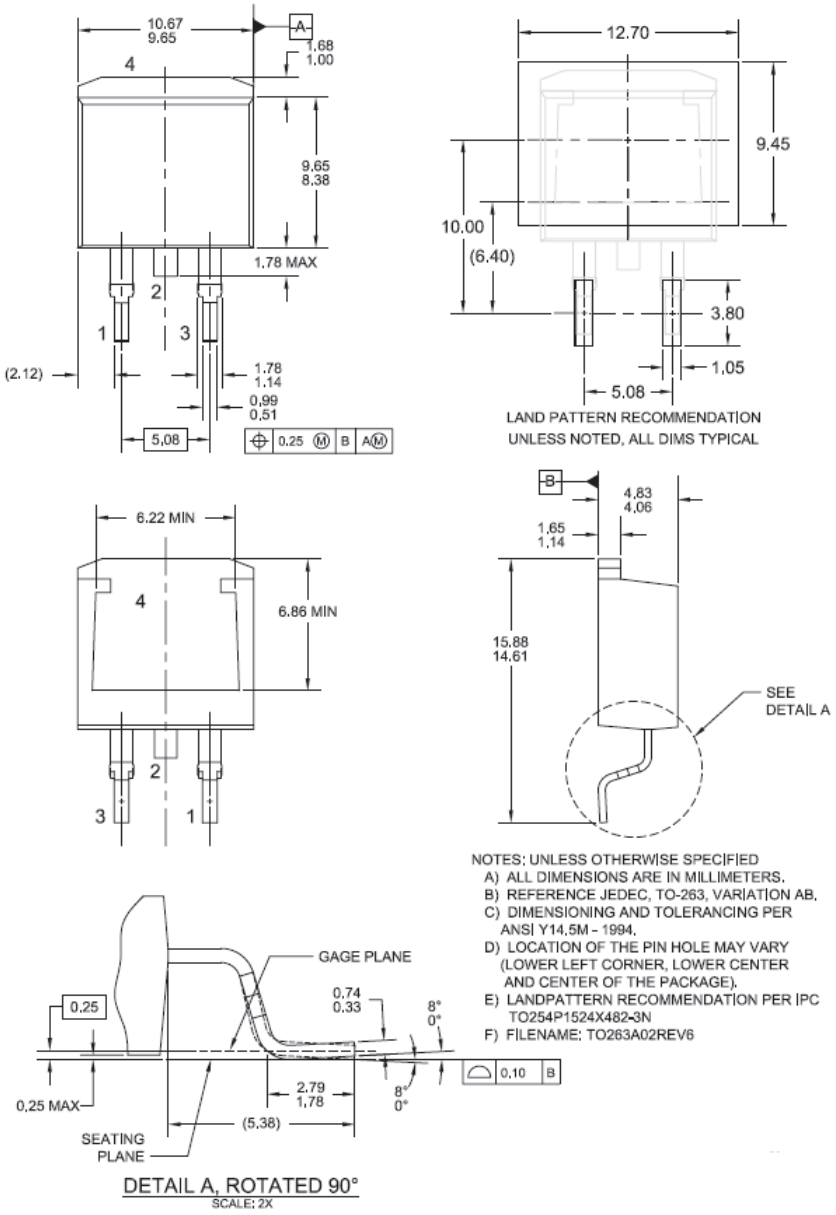



**Figure 16. 2LD,TO263, Surface Mount**

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Dimension in Millimeters

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